

# ZXCT1010

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## ENHANCED HIGH-SIDE CURRENT MONITOR

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### DESCRIPTION

The ZXCT1010 is a high side current sense monitor. Using this device eliminates the need to disrupt the ground plane when sensing a load current.

It is an enhanced version of the ZXCT1009 offering reduced typical output offset and improved accuracy at low sense voltage.

The wide input voltage range of 20V down to as low as 2.5V make it suitable for a range of applications. A minimum operating current of just 4 $\mu$ A, combined with its SOT23-5 package make suitable for portable battery equipment.

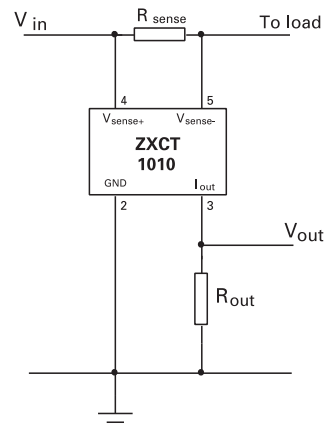
### FEATURES

- Low cost, accurate high-side current sensing
- Output voltage scaling
- Up to 2.5V sense voltage
- 2.5V – 20V supply range
- 300nA typical offset current
- 3.5 $\mu$ A quiescent current
- 1% typical accuracy
- SOT23 -5 package

### APPLICATIONS

- Battery chargers
- Smart battery packs
- DC motor control
- Over current monitor
- Power management
- Programmable current source

### APPLICATION CIRCUIT



### ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXCT1010E5TA	7"	8mm	3,000 units

PARTMARK 101  
PACKAGE SOT23-5

# ZXCT1010

## ABSOLUTE MAXIMUM RATINGS

Voltage on any pin	-0.6V to 20V (relative to GND)
Continuous output current, $I_{OUT}$	25mA
Continuous sense voltage, $V_{SENSE}^2$	-0.5V to +5V
Operating temperature, $T_A$	-40 to 85°C
Storage temperature	-55 to 150°C
Package power dissipation SOT23-5	( $T_A = 25^\circ\text{C}$ ) 300mW

Operation above the absolute maximum rating may cause device failure.

Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.

## ELECTRICAL CHARACTERISTICS

Test Conditions  $T_A = 25^\circ\text{C}$ ,  $V_{in} = 5\text{V}$ ,  $R_{out} = 100\Omega$ .

SYMBOL	PARAMETER	CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
$V_{in}$	$V_{CC}$ Range		2.5		20	V
$I_{out}^1$	Output current	$V_{sense} = 0\text{V}$	0	0.3	10	$\mu\text{A}$
		$V_{sense} = 10\text{mV}$	85	100	115	$\mu\text{A}$
		$V_{sense} = 100\text{mV}$	0.975	1.00	1.025	mA
		$V_{sense} = 200\text{mV}$	1.95	2.00	2.05	mA
		$V_{sense} = 1\text{V}$	9.7	10.0	10.3	mA
$I_q$	Ground pin current	$V_{sense} = 0\text{V}$		3.5	8	$\mu\text{A}$
$V_{sense}^2$	Sense Voltage		0		2500	mV
$I_{sense}^-$	$V_{sense}^-$ input current				100	nA
Acc	Accuracy	$R_{sense} = 0.1\Omega$ $V_{sense} = 200\text{mV}$	-2.5		2.5	%
Gm	Transconductance, $I_{out} / V_{sense}$			10000		$\mu\text{A/V}$
BW	Bandwidth	$V_{SENSE(DC)} = 10\text{mV}$ , Pin = -40dBm ‡		300		kHz
		$V_{SENSE(DC)} = 100\text{mV}$ , Pin = -20dBm ‡		2		MHz

<sup>1</sup> Includes input offset voltage contribution

<sup>2</sup>  $V_{SENSE}$  is defined as the differential voltage between  $V_{SENSE+}$  and  $V_{SENSE-}$ .

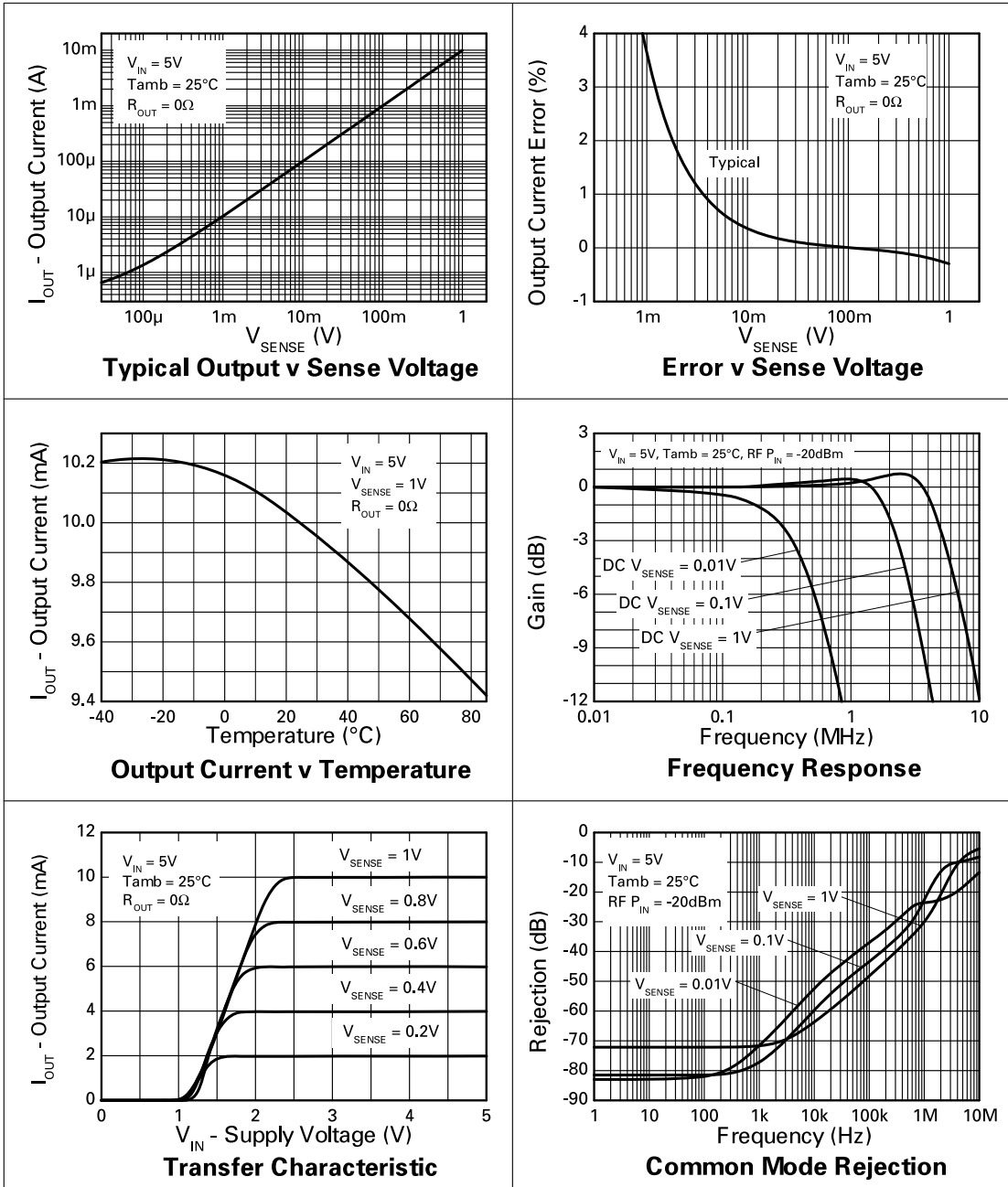
$$V_{SENSE} = V_{SENSE+} - V_{SENSE-}$$

$$= V_{IN} - V_{LOAD}$$

$$= I_{LOAD} \times R_{SENSE}$$

<sup>3</sup> -20dBm=63mVp-p into 50 $\Omega$

## TYPICAL CHARACTERISTICS

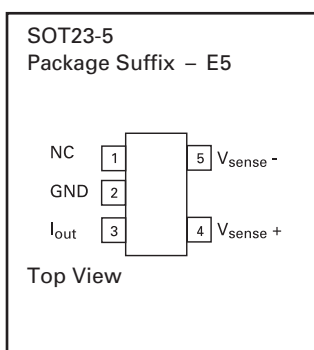


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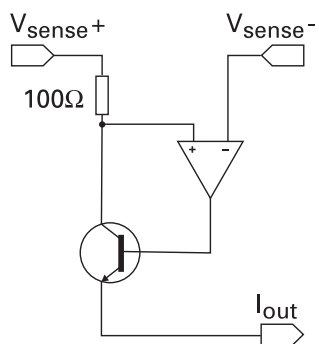
## PIN DESCRIPTION

Pin Name	Pin Function
$V_{sense+}$	Supply voltage
$V_{sense-}$	Connection to load/battery
$I_{out}$	Output current, proportional to $V_{in}-V_{load}$
GND	Ground

## CONNECTION DIAGRAM



## SCHEMATIC DIAGRAM



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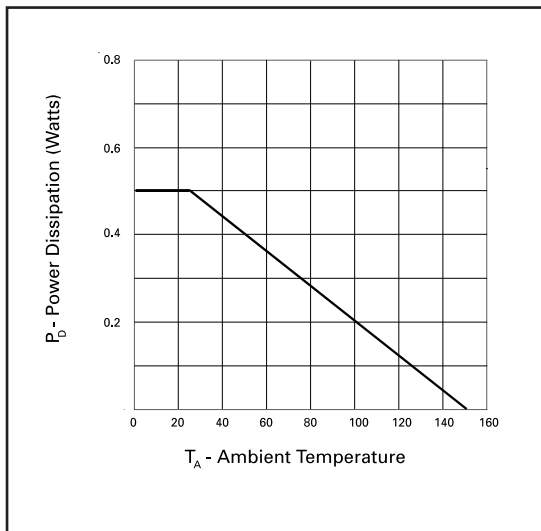
## POWER DISSIPATION

The maximum allowable power dissipation of the device for normal operation ( $P_{max}$ ), is a function of the package junction to ambient thermal resistance ( $\theta_{ja}$ ), maximum junction temperature ( $T_{jmax}$ ), and ambient temperature ( $T_{amb}$ ), according to the expression:

$$P_{max} = (T_{jmax} - T_{amb}) / \theta_{ja}$$

The device power dissipation,  $P_D$  is given by the expression:

$$P_D = I_{out} \cdot (V_{in} - V_{out}) \text{ Watts}$$



## APPLICATIONS INFORMATION

The following lines describe how to scale a load current to an output voltage.

$$V_{sense} = V_{in} - V_{load}$$

$$V_{out} = 0.01 \times V_{sense} \times R_{out}^1$$

E.g.

A 1A current is to be represented by a 100mV output voltage:

1) Choose the value of  $R_{sense}$  to give  $50mV > V_{sense} > 500mV$  at full load.

For example  $V_{sense} = 100mV$  at 1.0A.  $R_{sense} = 0.1/1.0 \Rightarrow 0.1 \text{ ohms}$ .

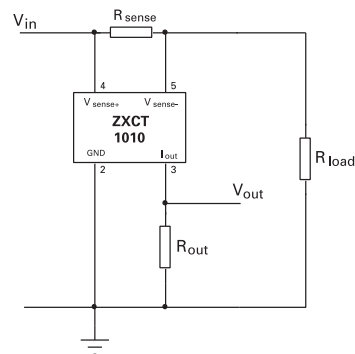
2) Choose  $R_{out}$  to give  $V_{out} = 100mV$ , when  $V_{sense} = 100mV$ .

Rearranging <sup>1</sup> for  $R_{out}$  gives:

$$R_{out} = V_{out} / (V_{sense} \times 0.01)$$

$$R_{out} = 0.1 / (0.1 \times 0.01) = 100 \Omega$$

## TYPICAL CIRCUIT APPLICATION



Where  $R_{load}$  represents any load including DC motors, a charging battery or further circuitry that requires monitoring,  $R_{sense}$  can be selected on specific requirements of accuracy, size and power rating.



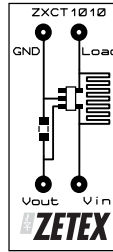
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## APPLICATIONS INFORMATION (Continued)

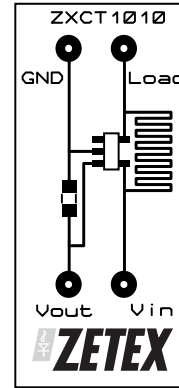
### PCB trace shunt resistor for low cost solution

The figure below shows output characteristics of the device when using a PCB resistive trace for a low cost solution in replacement for a conventional shunt resistor. The graph shows the linear rise in voltage across the resistor due to the PTC of the material and demonstrates how this rise in resistance value over temperature compensates for the NTC of the device.

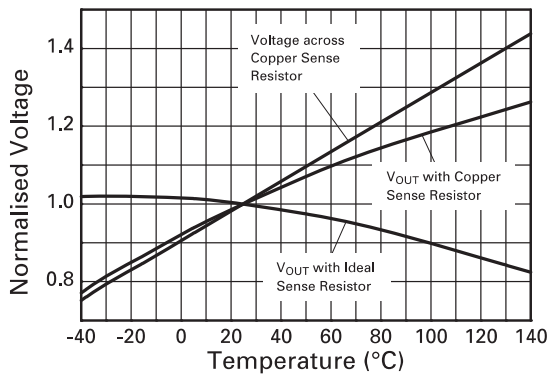
The figure opposite shows a PCB layout suggestion. The resistor section is 25mm x 0.25mm giving approximately 150mΩ using 1oz copper. The data for the normalised graph was obtained using a 1A load current and a 100Ω output resistor. An electronic version of the PCB layout is available at [www.zetex.com/isense](http://www.zetex.com/isense)



Actual Size



Layout shows area of shunt resistor compared to SOT23-5 package. Not actual size



Effect of Sense Resistor Material on Temperature Performance

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"Not recommended for new designs"Device is still in production to support existing designs and production

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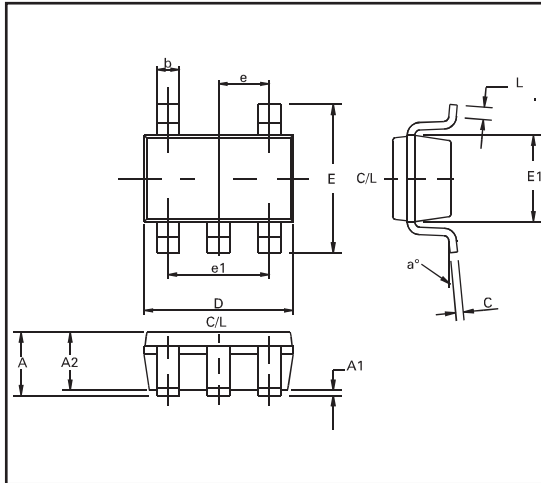
"Draft version" This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.

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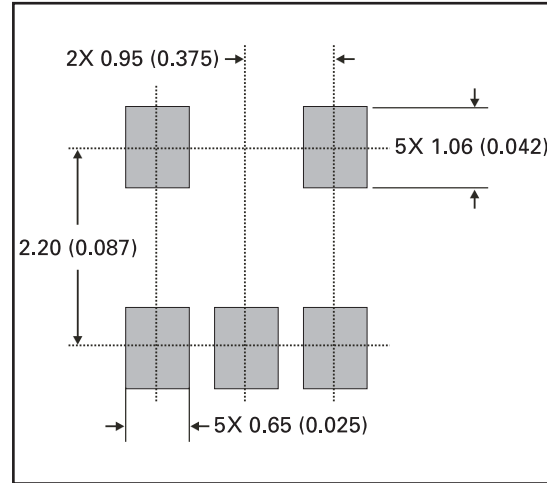


# ZXCT1010

## PACKAGE DIMENSIONS



## PAD LAYOUT DETAILS



Controlling dimensions are in millimeters. Approximate conversions are given in inches

## PACKAGE DIMENSIONS

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	0.90	1.45	0.035	0.057	E	2.60	3.00	0.102	0.118
A1	0.00	0.15	0.00	0.006	E1	1.50	1.75	0.059	0.069
A2	0.90	1.3	0.035	0.051	e	0.95 REF		0.037 REF	
b	0.35	0.50	0.014	0.020	e1	1.90 REF		0.075 REF	
C	0.09	0.20	0.0035	0.008	L	0.10	0.60	0.004	0.024
D	2.80	3.00	0.110	0.118	a°	0	10	0	10

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